Build Up HDI (Standard)

HDI08_1+6+1_1,60_35_engl

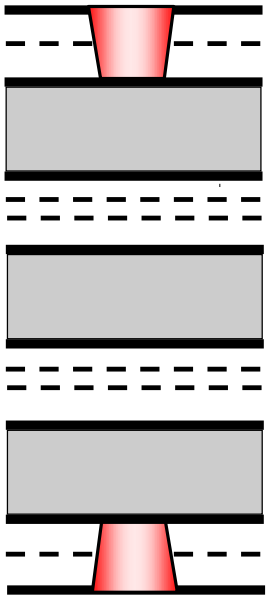
8 - Layers

Core: 0,30 mm Cu 35/35 µm

WE-Articel No.: | **1 + 6 + 1**

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	**60**	
	2			35 µm		**33**	
			0,300 mm			**300**	
	3			35 µm		**33**	
					1 x 1080 1 x 2116	**174**	
	4			35 µm		**33**	
			0,300 mm			**300**	
	5			35 µm		**33**	
					1 x 2116 1 x 1080	**174**	
	6			35 µm		**33**	
			0,300 mm			**300**	
	7			35 µm		**33**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1590

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,60**	+/-	0,13	mm				
thickness with electro plated Cu:	1,69	+/-	0,16	mm				
total thickness with soldermask	1,75	+/-	0,18	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
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